



PL-2303HX Edition (Chip Rev D) USB to Serial Bridge Controller Product Datasheet

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Revision History

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Table of Contents

1.0	FEATURES.....	8
2.0	FUNCTIONAL BLOCK DIAGRAM.....	9
3.0	INTRODUCTION	10
4.0	PIN ASSIGNMENT OUTLINE	11
4.1	SSOP28 Package	11
4.2	QFN32 Package.....	12
5.0	PIN ASSIGNMENT & DESCRIPTION.....	13
5.1	SSOP28 Package	13
5.2	QFN32 Package.....	14
6.0	USB STANDARD DESCRIPTORS	15
6.1	Device Descriptor.....	15
6.2	Configuration Descriptor.....	15
6.3	Interface Descriptor.....	16
6.4	Endpoint 1 Descriptor: Interrupt Input Endpoint.....	16
6.5	Endpoint 2 Descriptor: Bulk Data Output endpoint.....	16
6.6	Endpoint 3 Descriptor: Bulk Data Input endpoint	17
6.7	String Descriptors.....	17
7.0	USB STANDARD REQUESTS.....	18
8.0	DATA FORMATS & PROGRAMMABLE BAUD RATE GENERATOR.....	19
9.0	DC & TEMPERATURE CHARACTERISTICS.....	20
9.1	Absolute Maximum Ratings.....	20
9.2	DC Characteristics	20
9.3	Clock Characteristics	21
9.4	Temperature Characteristics	22
9.5	Leakage Current and Capacitance	22
9.6	Power-On Reset.....	22
10.0	OUTLINE DIAGRAM.....	23
10.1	SSOP28 Package	23
10.2	QFN32 Package.....	24

11.0 REEL PACKING INFORMATION	25
11.1 Carrier Tape (SSOP-28).....	25
11.2 Reel Dimension	26
12.0 ORDERING INFORMATION	26

List of Figures

Figure 2-1 Block Diagram of PL-2303HX (Rev D).....	9
Figure 4-1 Pin Assignment Outline of PL-2303HX (Rev D) SSOP28	11
Figure 4-2 Pin Assignment Outline of PL-2303HX (Rev D) QFN32.....	12
Figure 10-1 Power-On Reset Diagram.....	22
Figure 10-1 Outline Diagram of PL-2303HX (Rev D) SSOP28	23
Figure 10-2 Outline Diagram of PL-2303HX (Rev D) QFN32.....	24
Figure 11-1a SSOP28 Carrier Tape	25
Figure 11-1b IC Reel Placements	25
Figure 11-2 Reel Dimension	26

List of Tables

Table 5-1 Pin Assignment & Description (SSOP28)	13
Table 5-2 Pin Assignment & Description (QFN32)	14
Table 6-1 Device Descriptor.....	15
Table 6-2 Configuration Descriptor	15
Table 6-3 Interface Descriptor.....	16
Table 7-4 Endpoint1 Descriptor.....	16
Table 6-5 Endpoint2 Descriptor.....	16
Table 6-6 Endpoint3 Descriptor.....	17
Table 6-7a String Descriptor – Language ID	17
Table 6-7b String Descriptor – Manufacturer.....	17
Table 6-7c String Descriptor – Product	18
Table 6-7d String Descriptor – Serial Number	18
Table 8-1 Supported Data Formats	19
Table 8-2 Baud Rate Settings (Supported by Driver)	19
Table 9-1 Absolute Maximum Ratings.....	20
Table 9-2a Operating Voltage and Suspend Current.....	20
Table 9-2b 3.3V I/O Pins.....	20
Table 9-2c VDD_325@3.3V Serial I/O Pins	21
Table 9-2d VDD_325@2.5V Serial I/O Pins.....	21
Table 9-2e VDD_325@1.8V Serial I/O Pins.....	21
Table 9-3 Clock Characteristics	21
Table 9-4 Temperature Characteristics	22
Table 9-5 Leakage Current and Capacitance.....	22
Table 9-6 Power-On Reset	22

Table 10-1 Package Dimension.....	23
Table 11-2 Reel Part Number Information	26
Table 12-1 Ordering Information.....	26

1.0 Features

- Fully Compliant with USB Specification v2.0 (Full-Speed)
- On Chip USB 1.1 transceiver, 5V→3.3V regulator
- On-chip 96MHz clock generator
- Supports RS-422/RS-485 like serial interface (TXD, DTR_N, and RTS_N pins should be externally pulled-up to 5V)
- Supports RS232-like Serial Interface
 - Full-duplex transmitter and receiver (TXD and RXD)
 - Six MODEM control pins (RTS, CTS, DTR, DSR, DCD, and RI)
 - 5, 6, 7 or 8 data bits
 - Odd, Even, Mark, Space, or None parity mode
 - One, one and a half, or two stop bits
 - Parity error, frame error, and serial break detection
 - Programmable baud rate from 75 bps to 12M bps
 - External RS232 driver power down control
 - Independent power source for serial interface
- Extensive Flow Control Mechanism
 - Adjustable high/low watermark level
 - Automatic hardware flow control with CTS/RTS⁽¹⁾ or DSR/DTR⁽²⁾
 - Automatic software flow control with XON/XOFF
 - Inbound data buffer overflow detection
- Configurable 512-byte bi-directional data buffer
 - 256-byte outbound buffer and 256-byte inbound buffer; or
 - 128-byte outbound buffer and 384-byte inbound buffer
- Supports remote wake-up from MODEM input signals
- Four (4) General Purpose I/O (GP0, GP1, GP2, & GP3) pins & Four (4) Auxiliary General Purpose I/O (RI_N, DSR_N, DCD_N, & CTS_N) pins.
- On-chip OTP (One Time Programming) ROM for startup device configurations
- Hardware backward compatible with PL-2303H
- Provides drivers support for Windows, Mac OS, Linux, and WinCE
- [Windows 7, Vista, XP Certified Logo Drivers \(x86 and x64\)](#)
- [USB-IF Logo Compliant with TID 40000100](#)
- Small footprint 28-pin SSOP or 32-pin QFN IC package

Notes:

(1) – CTS/RTS Hardware Flow Control supports either low-level active or high-level active.

(2) – For DSR/DTR Hardware Flow Control support, please contact Prolific FAE for more information.

2.0 Functional Block Diagram

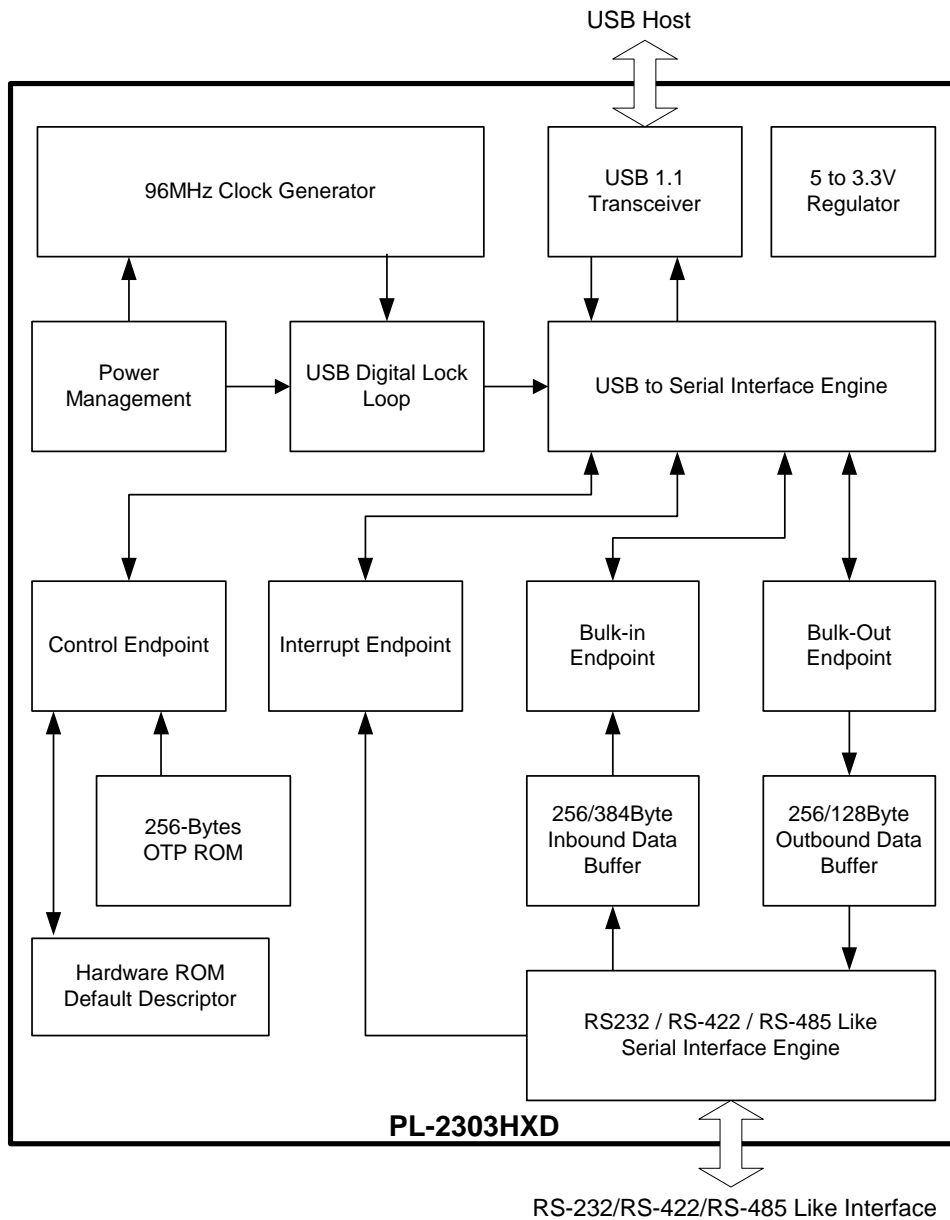


Figure 2-1 Block Diagram of PL-2303HX (Rev D)

3.0 Introduction

PL-2303HX provides a convenient solution for connecting an RS232-like full-duplex asynchronous serial device to any Universal Serial Bus (USB) capable host. PL-2303HX highly compatible drivers could simulate the traditional COM port on most operating systems allowing the existing applications based on COM port to easily migrate and be made USB ready.

By taking advantage of USB bulk transfer mode, large data buffers, and automatic flow control, PL-2303HX is capable of achieving higher throughput compared to traditional UART (Universal Asynchronous Receiver Transmitter) ports. When real RS232 signaling is not required, baud rate higher than 115200 bps could be used for even higher performance. The flexible baud rate generator of PL-2303HX could be programmed to generate any rate between 75 bps to 12M bps.

PL-2303HX is exclusively designed for mobile and embedded solutions in mind, providing a small footprint that could easily fit in to any connectors and handheld devices. With very small power consumption in either operating or suspend mode, PL-2303HX is perfect for bus powered operation with plenty of power left for the attached devices. Flexible signal level requirement on the RS232-like serial port side also allows PL-2303HX to connect directly to any 3.3V~1.8V range devices.

4.0 Pin Assignment Outline

4.1 SSOP28 Package

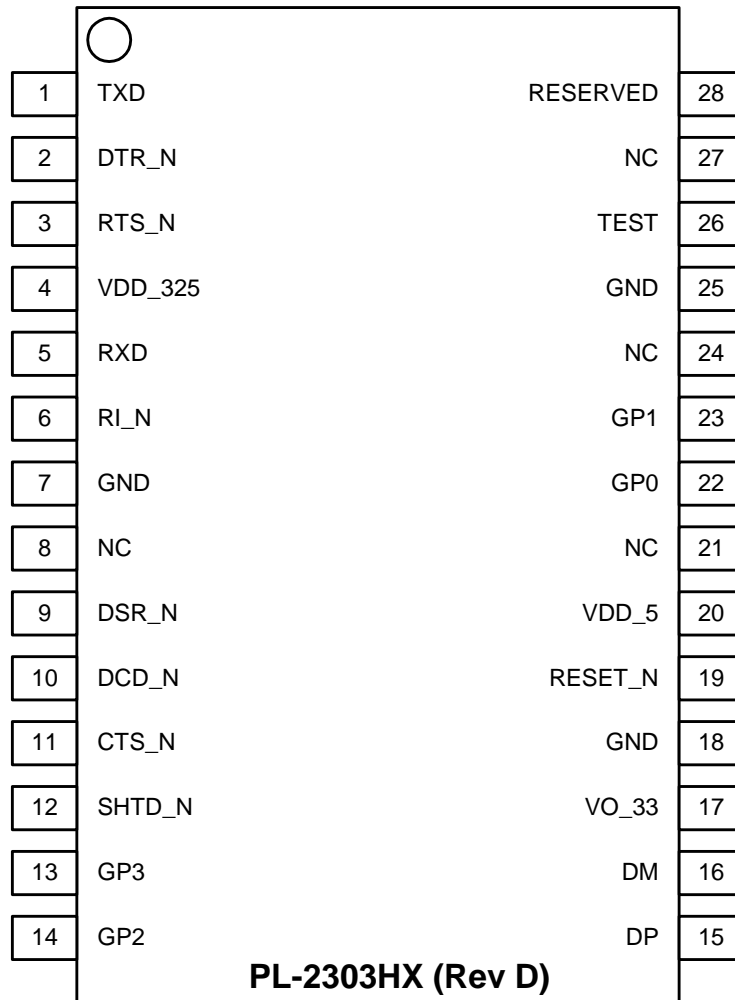


Figure 4-1 Pin Assignment Outline of PL-2303HX (Rev D) SSOP28

4.2 QFN32 Package

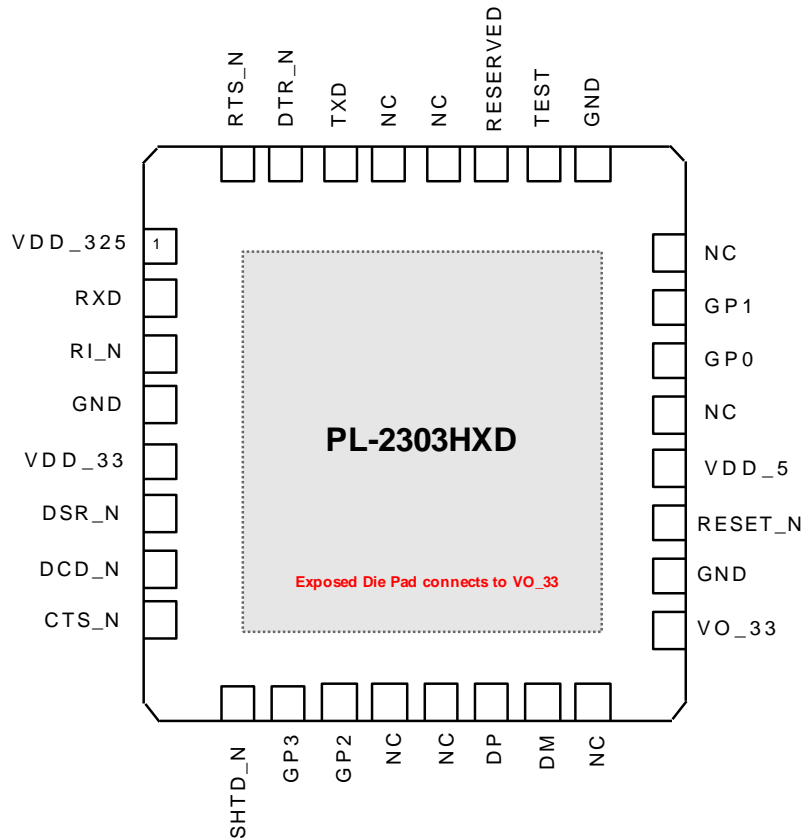
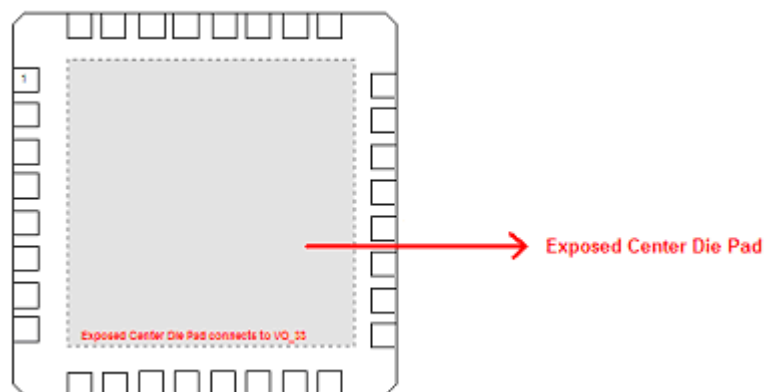


Figure 4-2 Pin Assignment Outline of PL-2303HX (Rev D) QFN32

Warning: The exposed center die pad of the PL-2303HX QFN package is connected (bonded) to the pin VO_33 so it is very important to design the PCB layout wherein this exposed die pad won't get grounded on the PCB when mounted.



5.0 Pin Assignment & Description

Pin Type Abbreviation:

I: Input

O: Output

B: Bidirectional I/O

P: Power/Ground

5.1 SSOP28 Package

Table 5-1 Pin Assignment & Description (SSOP28)

Pin #	Name	Type	Description
1	TXD	O ⁽¹⁾	Serial Port (Transmitted Data)
2	DTR_N	O ⁽¹⁾	Serial Port (Data Terminal Ready)
3	RTS_N	O ⁽¹⁾	Serial Port (Request To Send)
4	VDD_325	P	RS232 VDD. The power pin for the serial port signals. When the serial port is 3.3V, this should be 3.3V. When the serial port is 2.5V, this should be 2.5V. The range can be from 1.8V~3.3V.
5	RXD	I ⁽²⁾	Serial Port (Received Data)
6	RI_N	B ⁽²⁾	Serial Port (Ring Indicator); or Auxiliary General Purpose I/O Port when enabled ⁽⁷⁾ .
7	GND	P	Ground
8	NC	-	No Connection
9	DSR_N	B ⁽²⁾	Serial Port (Data Set Ready); or Auxiliary General Purpose I/O Port when enabled ⁽⁷⁾ .
10	DCD_N	B ⁽²⁾	Serial Port (Data Carrier Detect); or Auxiliary General Purpose I/O Port when enabled ⁽⁷⁾ .
11	CTS_N	B ⁽²⁾	Serial Port (Clear to Send); or Auxiliary General Purpose I/O Port when enabled ⁽⁷⁾ .
12	SHTD_N	O ⁽³⁾	RS232 Transceiver Shut Down Control
13	GP3	I/O	Auxiliary GPIO Pin 3 (Default output high mode) ⁽⁶⁾
14	GP2	I/O	Auxiliary GPIO Pin 2 (Default output high mode) ⁽⁶⁾
15	DP	B	USB Port D+ signal
16	DM	B	USB Port D- signal
17	VO_33	P	Regulator Power Output, 3.3V
18	GND	P	Ground
19	RESET_N	I ⁽⁴⁾	External System Reset (Active Low)
20	VDD_5	P	USB Port V _{BUS} , 5V Power. (6.5V for OTPROM writing voltage).
21	NC	-	No Connection
22	GP0	B ⁽⁵⁾	General Purpose I/O Pin 0
23	GP1	B ⁽⁵⁾	General Purpose I/O Pin 1
24	NC	-	No Connection
25	GND	-	Ground
26	TEST	I	Test mode control
27	NC	-	No Connection
28	Reserved	-	Reserved pin (Must be floating)

Notes:

- (1) – Tri-State, Output Pad. Level and Driving Capability decided by VDD_325.
- (2) – Tri-State, CMOS Input/Output Pad with level shifter. Level and Driving Capability decided by VDD_325.
- (3) – CMOS Output Pad.
- (4) – CMOS Input Pad, 5V tolerant.
- (5) – Tri-State, CMOS Input/Output Pad. (Default mode: Input)
- (6) – Default output high mode; do not connect to ground.
- (7) – Enabling Auxiliary GPIO requires special customized driver.

5.2 QFN32 Package

Table 5-2 Pin Assignment & Description (QFN32)

Pin #	Name	Type	Description
1	VDD_325	P	RS232 VDD. The power pin for the serial port signals. When the serial port is 3.3V, this should be 3.3V. When the serial port is 2.5V, this should be 2.5V. The range can be from 1.8V~3.3V.
2	RXD	I ⁽²⁾	Serial Port (Received Data)
3	RI_N	B ⁽²⁾	Serial Port (Ring Indicator); or Auxiliary General Purpose I/O Port when enabled ⁽⁶⁾ .
4	GND	P	Ground
5	VDD_33	P	Primary Power (3.3V)
6	DSR_N	B ⁽²⁾	Serial Port (Data Set Ready); or Auxiliary General Purpose I/O Port when enabled ⁽⁶⁾ .
7	DCD_N	B ⁽²⁾	Serial Port (Data Carrier Detect); or Auxiliary General Purpose I/O Port when enabled ⁽⁶⁾ .
8	CTS_N	B ⁽²⁾	Serial Port (Clear to Send); or Auxiliary General Purpose I/O Port when enabled ⁽⁶⁾ .
9	SHTD_N	O ⁽³⁾	RS232 Transceiver Shut Down Control
10	GP3	I/O	Auxiliary GPIO Pin 3 (Default output high mode) ⁽⁵⁾
11	GP2	I/O	Auxiliary GPIO Pin 2 (Default output high mode) ⁽⁵⁾
12	NC	-	No Connection
13	NC	-	No Connection
14	DP	B	USB Port D+ signal
15	DM	B	USB Port D- signal
16	NC	-	No Connection
17	VO_33	P	Regulator Power Output, 3.3V
18	GND	P	Ground
19	RESET_N	I	External System Reset (Active Low)
20	VDD_5	P	USB Port V _{BUS} , 5V Power.
21	NC	-	No Connection
22	GP0	B ⁽⁴⁾	General Purpose I/O Pin 0
23	GP1	B ⁽⁴⁾	General Purpose I/O Pin 1
24	NC	-	No Connection
25	GND	P	Ground
26	TEST	I	Test mode control
27	Reserved	-	Reserved pin (Must be floating)
28	NC	-	No Connection
29	NC	-	No Connection
30	TXD	O ⁽¹⁾	Serial Port (Transmitted Data)
31	DTR_N	O ⁽¹⁾	Serial Port (Data Terminal Ready)
32	RTS_N	O ⁽¹⁾	Serial Port (Request To Send)
IC Bottom PAD		P	Connects to VO_33 (Regulator Power Output, 3.3V)

Notes:

- (1) – Tri-State, Output Pad. Level and Driving Capability decided by VDD_325.
 (2) – Tri-State, CMOS Input/Output Pad with level shifter. Level and Driving Capability decided by VDD_325.
 (3) – CMOS Output Pad.
 (4) – Tri-State, CMOS Input/Output Pad. (Default mode: Input)
 (5) – Default output high mode; do not connect to ground.
 (6) – Enabling Auxiliary GPIO requires special customized driver.

6.0 USB Standard Descriptors

PL-2303HX supports one configuration with one interface and four endpoints. The descriptors are basically stored in an internal hardware ROM. However, some fields could be optionally modified by properly programmed on-chip OTPROM. The contents of all descriptors are shown in the following sections and the format of OTPROM would be given in later chapter.

6.1 Device Descriptor

Table 6-1 Device Descriptor

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	12h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	01h	DEVICE descriptor type
2	<i>bcdUSB</i>	Word	0110h	USB Specification Release Number 1.1
4	<i>bDeviceClass</i>	Byte	00h	
5	<i>bDeviceSubClass</i>	Byte	00h	
6	<i>bDeviceProtocol</i>	Byte	00h	
7	<i>bMaxPacketSize0</i>	Byte	40h	Maximum packet size for endpoint zero is 64
8	<i>idVender</i>	Word	067Bh	Vender ID ⁽¹⁾
10	<i>idProduct</i>	Word	2303h	Product ID ⁽¹⁾
12	<i>bcdDevice</i>	Word	0400h	Device Release Number ⁽¹⁾
14	<i>iManufacturer</i>	Byte	01h	Manufacturer string descriptor index
15	<i>iProduct</i>	Byte	02h	Product name string descriptor index
16	<i>iSerialNumber</i>	Byte	00h/03h	Serial number string descriptor index ⁽²⁾
17	<i>bNumConfigurations</i>	Byte	01h	One configuration.

Notes:

- (1) – The Vender ID, Product ID, and Device Release Number could be replaced by the contents of the on-chip OTPROM.
 (2) – The serial number string descriptor index could be defined by the contents of the on-chip OTPROM. If specified, the index will be 3 instead of 0.

6.2 Configuration Descriptor

Table 6-2 Configuration Descriptor

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	09h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	02h	CONFIGURATION descriptor type
2	<i>wTotalLength</i>	Word	0027h	Total length of data returned for this configuration.
4	<i>bNumInterface</i>	Byte	01h	One interface for this device.
5	<i>bConfigurationValue</i>	Byte	01h	
6	<i>iConfiguration</i>	Byte	00h	
7	<i>bmAttributes</i>	Byte	A0h/80h	Characteristic attributes ⁽³⁾
8	<i>MaxPower</i>	Byte	32h/FAh	Maximum power consumption ⁽⁴⁾

Notes:

- (3) – The Remote Wakeup attribute (bit 5) depends on the settings of the Remote Wakeup Enable (bit 0 to 4 of Device

Configuration Register 2). If all remote wakeup sources are disabled, the *bmAttributes* will be 80h. Otherwise, A0h is returned to indicate that this device is Remote Wakeup capable.

- (4) – The value of maximum power consumption depends on the *LD_MODE* (bit 5 of Device Configuration Register 2) parameter. If it is set to 1, the *MaxPower* byte will be FAh for it requires 500mA from the system. Otherwise, it is 32h that indicates 100mA required.

6.3 Interface Descriptor

Table 6-3 Interface Descriptor

Offset	Field	Size	Value	Description
0	<i>BLength</i>	Byte	09h	Size of this descriptor (in bytes)
1	<i>BDescriptorType</i>	Byte	04h	INTERFACE descriptor type
2	<i>BInterfaceNumber</i>	Byte	00h	One interface only
3	<i>BAlternateSetting</i>	Byte	00h	No alternate interface
4	<i>BNumEndpoints</i>	Byte	03h	Three endpoints (excluding control endpoint)
5	<i>BInterfaceClass</i>	Byte	FFh	Vendor Specific Class
6	<i>BInterfaceSubClass</i>	Byte	00h	
7	<i>BInterfaceProtocol</i>	Byte	00h	
8	<i>IInterface</i>	Byte	00h	

6.4 Endpoint 1 Descriptor: Interrupt Input Endpoint

Table 7-4 Endpoint1 Descriptor

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	07h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	05h	ENDPOINT descriptor type
2	<i>bEndpointAddress</i>	Byte	81h	Input endpoint
3	<i>bmAttributes</i>	Byte	03h	Transfer type is INTERRUPT
4	<i>wMaxPacketSize</i>	Word	000Ah	Ten Bytes
6	<i>bInterval</i>	Byte	01h	Polling on every 1 ms interval

6.5 Endpoint 2 Descriptor: Bulk Data Output endpoint

Table 6-5 Endpoint2 Descriptor

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	07h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	05h	ENDPOINT descriptor type
2	<i>bEndpointAddress</i>	Byte	02h	Output endpoint
3	<i>bmAttributes</i>	Byte	02h	Transfer type is BULK
4	<i>wMaxPacketSize</i>	Word	0040h	64 bytes
6	<i>bInterval</i>	Byte	00h	Ignored field

6.6 Endpoint 3 Descriptor: Bulk Data Input endpoint

Table 6-6 Endpoint3 Descriptor

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	07h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	05h	ENDPOINT descriptor type
2	<i>bEndpointAddress</i>	Byte	83h	Input endpoint
3	<i>bmAttributes</i>	Byte	02h	Transfer type is BULK
4	<i>wMaxPacketSize</i>	Word	0040h	64 bytes
6	<i>bInterval</i>	Byte	00h	Ignored field

6.7 String Descriptors

PL-2303HX supports four string descriptors:

- Language ID
- Manufacturer
- Product
- Serial Number

Except for Serial Number, the other three string descriptors are stored in the internal Mask ROM, i.e. their contents are fixed. The Serial Number is a special case. If the on-chip OTPROM is not properly programmed, then the Serial Number would be hidden from the system. If the on-chip OTPROM is properly programmed, then the Serial Number will be read from the on-chip OTPROM.

The following tables demonstrate the current defined value for each descriptor:

6.7.1 String Descriptor 0 – Language ID

Table 6-7a String Descriptor – Language ID

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	04h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	03h	STRING descriptor type
2	<i>bLANGID[0]</i>	Word	0409h	English (United States)

6.7.2 String Descriptor 1 – Manufacturer

Table 6-7b String Descriptor – Manufacturer

Offset	Field	Size	Value	Description
0	<i>BLength</i>	Byte	32h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	03h	STRING descriptor type
2	<i>bSTRING</i>	—	⇒	“Prolific Technology Inc.” in UNICODE

6.7.3 String Descriptor 2 - Product

Table 6-7c String Descriptor – Product

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	30h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	03h	STRING descriptor type
2	<i>bSTRING</i>	—	⇒	“USB-Serial Controller C” in UNICODE

6.7.4 String Descriptor 3 – Serial Number

Table 6-7d String Descriptor – Serial Number

Offset	Field	Size	Value	Description
0	<i>bLength</i>	Byte	12h	Size of this descriptor (in bytes)
1	<i>bDescriptorType</i>	Byte	03h	STRING descriptor type
2	<i>bSTRING</i>	—	⇒	“X ₇ X ₆ X ₅ X ₄ X ₃ X ₂ X ₁ X ₀ ” in UNICODE

Note:

The size of Serial Number is fixed in PL-2303HX design. It must be exactly 8 UNICODE characters (or 16 bytes). Note that in USB Specification, this serial number must be unique for each device.

7.0 USB Standard Requests

PL-2303HX supports the following USB standard requests. For non-supported requests or requests with invalid parameters, PL-2303HX will respond with STALL packet.

- Clear Feature
- Get Configuration
- Get Descriptor
- Get Status
 - Device Status
 - Interface Status
 - Endpoint 0, 1, 2, and 3 Status
- Set Address
- Set Configuration
- Set Feature

Valid Feature Selector supported by PL-2303HX includes:

- DEVICE_REMOTE_WAKEUP (for Device)
- ENDPOINT_HALT (for all Endpoints)

8.0 Data Formats & Programmable Baud Rate Generator

The PL-2303HX (Chip Rev D) controller supports versatile data formats and has a programmable baud rate generator. The supported data formats are shown on Table 8-1. The programmable baud rate generator supports baud rates up to 12M bps and standard driver already supports several baud rate settings as shown in Table 8-2.

Table 8-1 Supported Data Formats

	Description
Stop bits	1 1.5 2
Parity type	None Odd Even Mark Space
Data bits	5, 6, 7, 8

Table 8-2 Baud Rate Settings (Supported by Driver)

Baud Rates (bps)	Baud Rates (bps)	Baud Rates (bps)	Baud Rates (bps)	Baud Rates (bps)
12000000				
6000000	614400	38400	7200	1200
3000000	460800	28800	4800	600
2457600	230400	19200	3600	300
1228800	115200	14400	2400	150
921600	57600	9600	1800	75

Note: For special baud rate requirements, please contact Prolific FAE for driver customization support.

9.0 DC & Temperature Characteristics

9.1 Absolute Maximum Ratings

Table 9-1 Absolute Maximum Ratings

Items	Ratings
Power Supply Voltage - VDD_5	-0.3 to 6.5 V
Input Voltage of 3.3V I/O	-0.3 to VO_33+0.3 V
Input Voltage of 3.3V I/O with 5V Tolerance I/O	-0.3 to VDD_5+0.3V
Output Voltage of 3.3V I/O	-0.3 to VDD_5 +0.3 V
Storage Temperature	-40 to 150 °C

9.2 DC Characteristics

9.2.1 Operating Voltage and Suspend Current

Table 9-2a Operating Voltage and Suspend Current

Parameter	Symbol	Min	Typ	Max	Unit
Operating Voltage Range	VDD_5	4.5	5	6.5	V
Output Voltage of Regulator	VO_33	2.97	3.3	3.63	V
Operating Current ⁽¹⁾ (Power Consumption)	I _{DD}	-	20	25	mA
Suspend Current	I _{SUS}	-	260	450	μA

Note: (1) – No device connected.

9.2.2 3.3V I/O Pins

Table 9-2b 3.3V I/O Pins

Parameter	Symbol	Min	Typ	Max	Unit
Output Driving Capability	I _{DD}		4		mA
Power Supply for 3.3V I/O Pins	VO_33	2.97	3.3	3.63	V
Input Voltage (CMOS)					
Low	V _{IL}	--	--	0.3* VO_33	V
High	V _{IH}	0.7* VO_33	--	--	V
Input Voltage (LVTTTL)					
Low	V _{IL}	--	--	0.8	V
High	V _{IH}	2.0	--	--	V
Output Voltage, 3.3V					
Low	V _{OL}	--	--	0.4	V
High	V _{OH}	2.4	--	--	V

9.2.3 Serial I/O Pins

Table 9-2c VDD_325@3.3V Serial I/O Pins

Parameter	Symbol	Min	Typ	Max	Unit
Output Driving Capability	I _{DD}		8		mA
Power Supply for Serial I/O Pins	VDD_325	2.97	3.3	3.63	V
Input Voltage					
Low	V _{IL}	--	--	0.25* VDD_325	V
High	V _{IH}	0.7* VDD_325	--	--	V
Output Voltage					
Low	V _{OL}	--	--	0.4	V
High	V _{OH}	2.4	--	--	V

Table 9-2d VDD_325@2.5V Serial I/O Pins

Parameter	Symbol	Min	Typ	Max	Unit
Output Driving Capability	I _{DD}		5.2		mA
Power Supply for Serial I/O Pins	VDD_325	2.25	2.5	2.75	V
Input Voltage					
Low	V _{IL}	--	--	0.25* VDD_325	V
High	V _{IH}	0.7* VDD_325	--	--	V
Output Voltage					
Low	V _{OL}	--	--	0.4	V
High	V _{OH}	1.85	--	--	V

Table 9-2e VDD_325@1.8V Serial I/O Pins

Parameter	Symbol	Min	Typ	Max	Unit
Output Driving Capability	I _{DD}		4.4		mA
Power Supply for Serial I/O Pins	VDD_325	1.65	1.8	1.95	V
Input Voltage					
Low	V _{IL}	--	--	0.25* VDD_325	V
High	V _{IH}	0.7* VDD_325	--	--	V
Output Voltage					
Low	V _{OL}	--	--	0.4	V
High	V _{OH}	1.25	--	--	V

9.3 Clock Characteristics

Table 9-3 Clock Characteristics

Parameter	Min	Typ	Max	Units
Frequency of Operation	11.97	12.0	12.03	MHz
Clock Period	83.1	83.3	83.5	ns
Duty Cycle	45	50	55	%

9.4 Temperature Characteristics

Table 9-4 Temperature Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Operating Temperature	--	-40	--	85	°C
Junction Operation Temperature	T _J	-40	25	105	°C

9.5 Leakage Current and Capacitance

Table 9-5 Leakage Current and Capacitance

Parameter	Symbol	Min	Typ	Max	Unit
Input Leakage Current*1	I _L	-10	±1	10	μA
Tri-state Leakage Current	I _{oz}	-10	±1	10	μA
Input Capacitance	C _{IN}	--	2.8	--	pF
Output Capacitance	C _{OUT}	2.7	--	4.9	pF
Bi-directional Buffer Capacitance	C _{BID}	2.7	--	4.9	pF

*1. No pull-up or pull-down resistor.

9.6 Power-On Reset

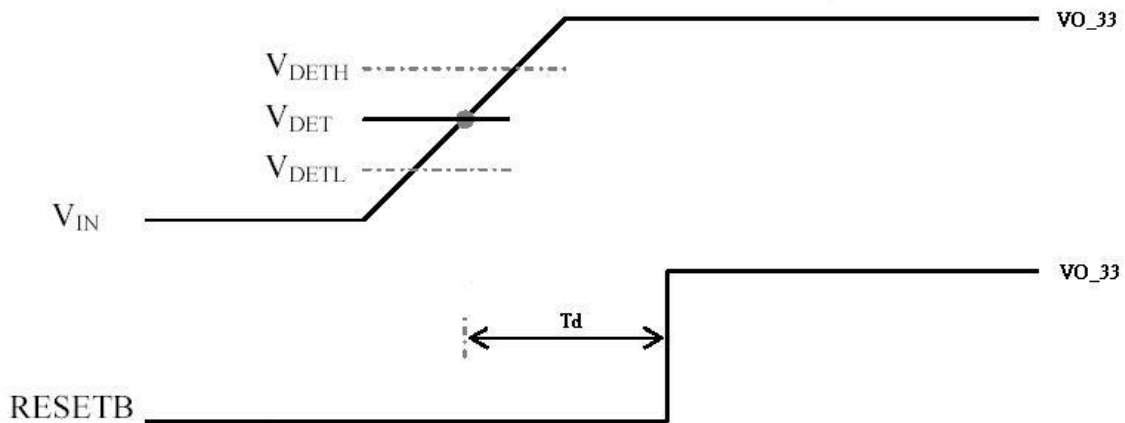


Figure 10-1 Power-On Reset Diagram

Table 9-6 Power-On Reset

Parameter	Symbol	FF@70°C	TT@25°C	SS@0°C	Unit
		VO_33=3.63V	VO_33=3.3V	VO_33=2.97V	
Output Delay Time	Td	1.18	2.68	182.5	μsec

Note: The delay time is simulated with VIN ramp of 1V/μsec.

10.0 Outline Diagram

10.1 SSOP28 Package

Table 10-1 Package Dimension

Symbol	Millimeter			Inch		
	Min	Nom	Max	Min	Nom	Max
b	0.22		0.38	0.009		0.015
E	7.40	7.80	8.20	0.291	0.307	0.323
E1	5.00	5.30	5.60	0.197	0.209	0.220
L	0.55	0.75	0.95	0.021	0.030	0.037
R1	0.09			0.004		
D	9.9	10.2	10.5	0.390	0.402	0.413
A			2.0			0.079
e		0.65			0.0256	
L1		1.25			0.050	
A1	0.05			0.020		
A2	1.65	1.75	1.85	0.065	0.069	0.073

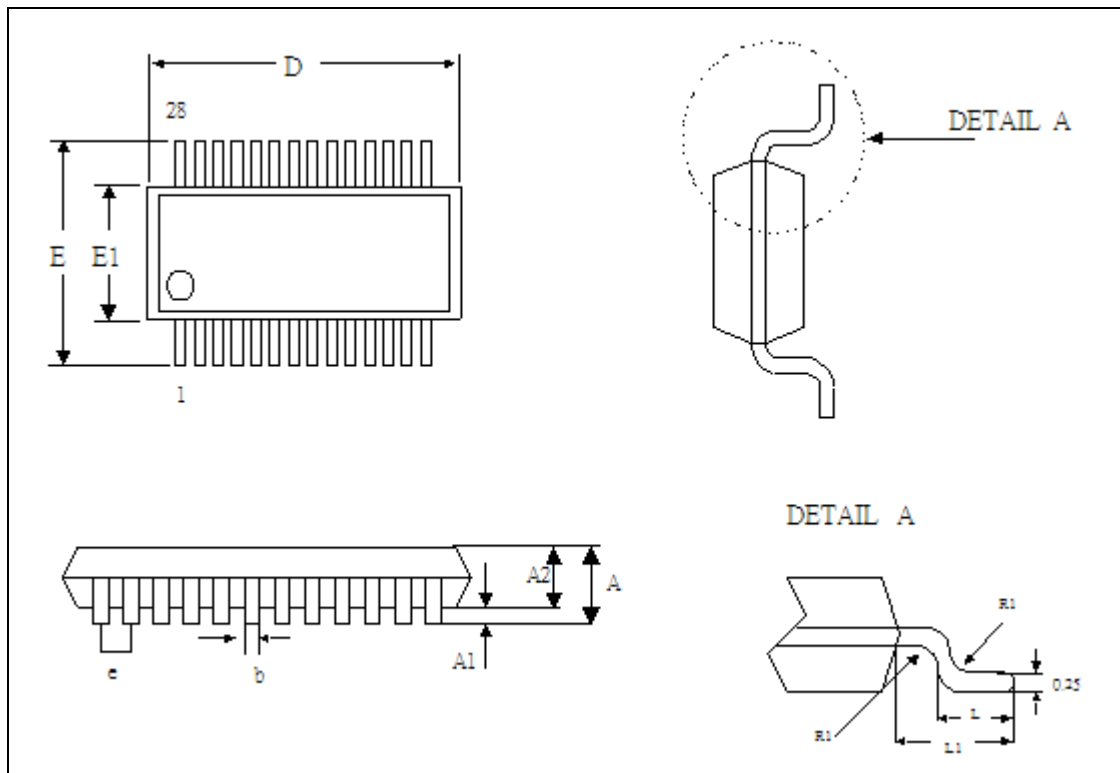


Figure 10-1 Outline Diagram of PL-2303HX (Rev D) SSOP28

10.2 QFN32 Package

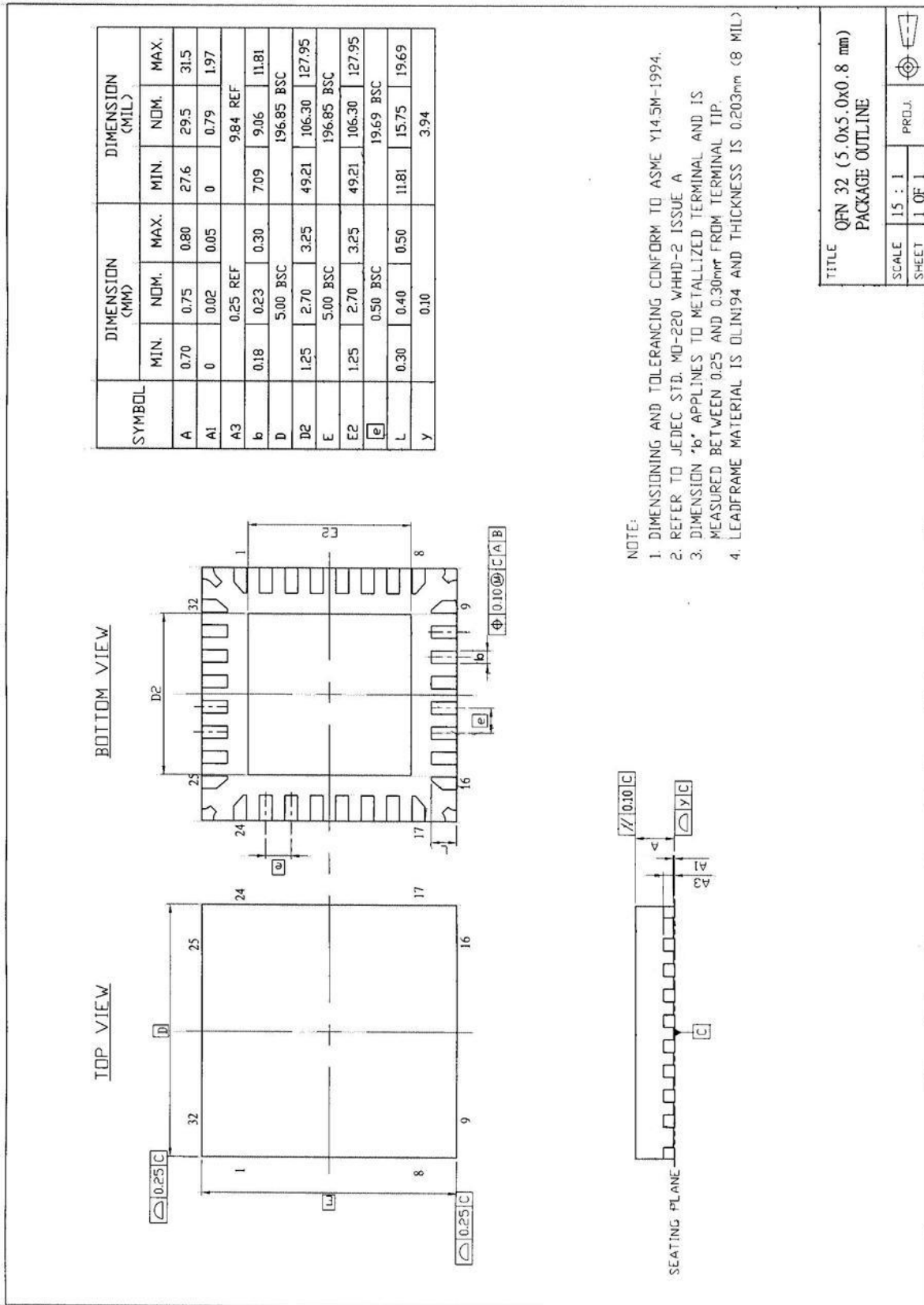


Figure 10-2 Outline Diagram of PL-2303HX (Rev D) QFN32

11.0 Reel Packing Information

11.1 Carrier Tape (SSOP-28)

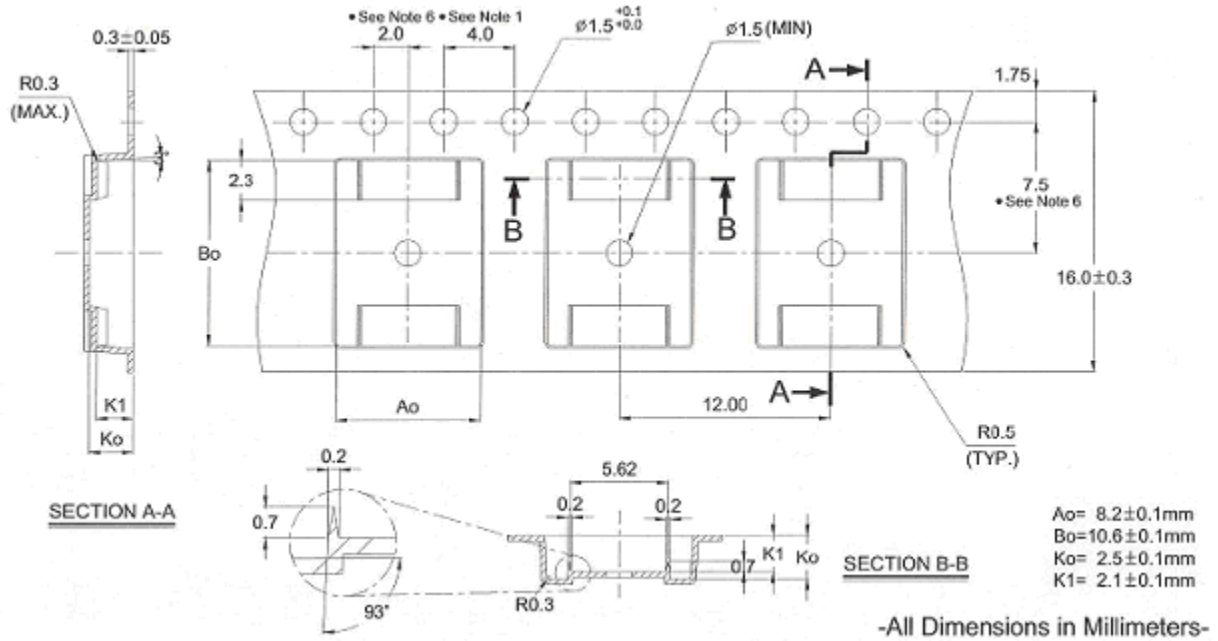


Figure 11-1a SSOP28 Carrier Tape

Notes:

1. 10 sprocket hole pitch cumulative tolerance ± 0.2
2. Camber not to exceed 1mm in 100mm.
3. Material: Black Polystyrene.
4. Ao and Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
7. IC quantity per one reel: 1,000 (min) ~ 2,000 (max)

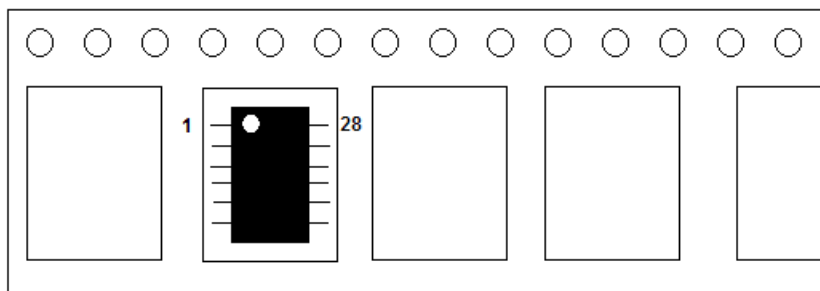


Figure 11-1b IC Reel Placements

11.2 Reel Dimension

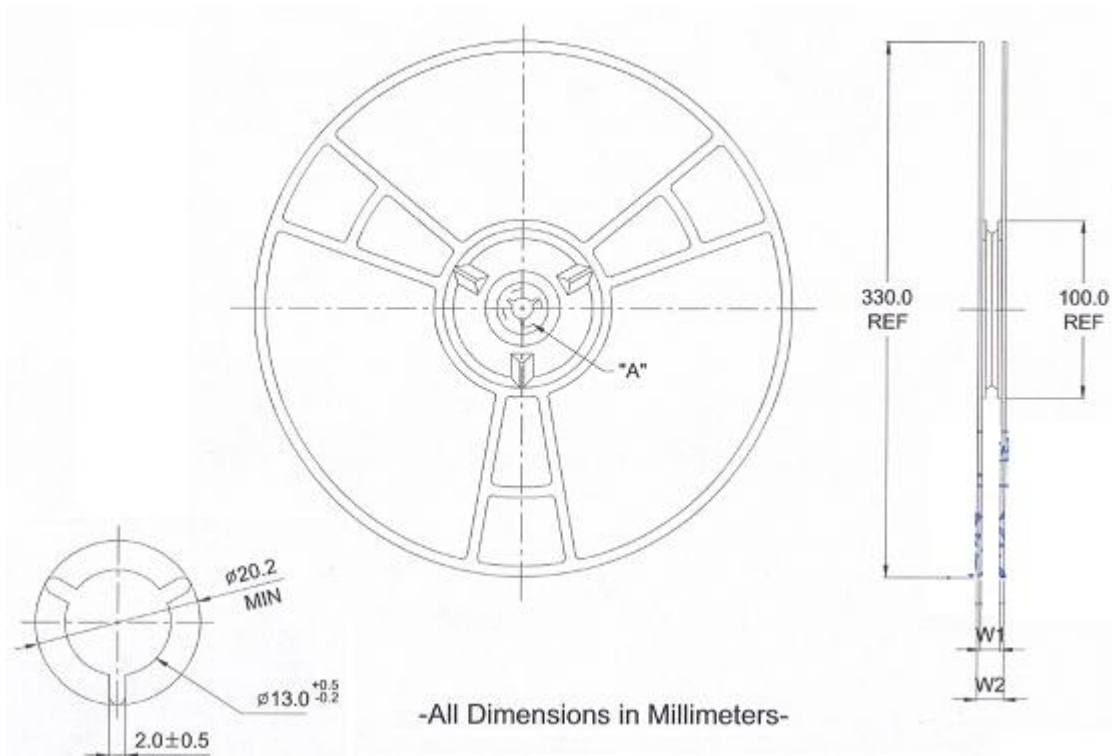


Figure 11-2 Reel Dimension

Table 11-2 Reel Part Number Information

Part Number	Normal Hub Width	W1 +0.3mm -0.2mm	W2 Max
RD33008SW-T + RD33008SW-T	16mm	16.8mm	22.2mm

12.0 Ordering Information

Table 12-1 Ordering Information

Part Number	Package Type
PL-2303HXD SSOP	28-pin SSOP
PL-2303HXD QFN	32-pin QFN
PL-2303HXD SSOP LF	28-pin SSOP (Lead Free or Pb-Free)
PL-2303HXD QFN LF	32-pin QFN (Lead Free or Pb-Free)

Note: The chip datecode and version can be found on the chip-marking showing: "YYWW1D".

Where: YY – last two digits of the year

WW – week of the year

1D – chip version

Example: "05201D" – means year 2005 + week no. 20 + 1D chip version.